

William J Song

List of Publications by Year in descending order

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Version: 2024-02-01

22
papers

982
citations

1307594

7
h-index

1199594

12
g-index

22
all docs

22
docs citations

22
times ranked

855
citing authors

| # | ARTICLE | IF | CITATIONS |
|----|--|-----|-----------|
| 1 | Improvements to seamless vertical handover between mobile WiMAX and 3GPP UTRAN through the evolved packet core. IEEE Communications Magazine, 2009, 47, 66-73. | 6.1 | 720 |
| 2 | Power Modeling for GPU Architectures Using McPAT. ACM Transactions on Design Automation of Electronic Systems, 2014, 19, 1-24. | 2.6 | 54 |
| 3 | Manifold: A parallel simulation framework for multicore systems. , 2014, , . | | 52 |
| 4 | A framework for architecture-level power, area, and thermal simulation and its application to network-on-chip design exploration. Performance Evaluation Review, 2011, 38, 63-68. | 0.6 | 24 |
| 5 | Architectural Reliability: Lifetime Reliability Characterization and Management of Many-Core Processors. IEEE Computer Architecture Letters, 2015, 14, 103-106. | 1.5 | 20 |
| 6 | Enhancements to FPMIPv6 for improved seamless vertical handover between LTE and heterogeneous access networks. IEEE Wireless Communications, 2013, 20, 112-119. | 9.0 | 15 |
| 7 | Energy-Efficient Acceleration of Deep Neural Networks on Realtime-Constrained Embedded Edge Devices. IEEE Access, 2020, 8, 216259-216270. | 4.2 | 15 |
| 8 | Duplo: Lifting Redundant Memory Accesses of Deep Neural Networks for GPU Tensor Cores. , 2020, , . | | 10 |
| 9 | Thermal system identification (TSI): A methodology for post-silicon characterization and prediction of the transient thermal field in multicore chips. , 2012, , . | | 9 |
| 10 | FineReg: Fine-Grained Register File Management for Augmenting GPU Throughput. , 2018, , . | | 9 |
| 11 | Energy Introspector: A parallel, composable framework for integrated power-reliability-thermal modeling for multicore architectures. , 2014, , . | | 8 |
| 12 | Control Principles and On-Chip Circuits for Active Cooling Using Integrated Superlattice-Based Thin-Film Thermoelectric Devices. IEEE Transactions on Very Large Scale Integration (VLSI) Systems, 2014, 22, 1909-1919. | 3.1 | 8 |
| 13 | Managing performance-reliability tradeoffs in multicore processors. , 2015, , . | | 8 |
| 14 | KitFox: Multiphysics Libraries for Integrated Power, Thermal, and Reliability Simulations of Multicore Microarchitecture. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2015, 5, 1590-1601. | 2.5 | 7 |
| 15 | Amdahl's law for lifetime reliability scaling in heterogeneous multicore processors. , 2016, , . | | 6 |
| 16 | SST: A Scalable Parallel Framework for Architecture-Level Performance, Power, Area and Thermal Simulation. Computer Journal, 2012, 55, 181-191. | 2.4 | 5 |
| 17 | Post-Silicon Characterization and On-Line Prediction of Transient Thermal Field in Integrated Circuits Using Thermal System Identification. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2014, 4, 37-45. | 2.5 | 3 |
| 18 | The Nebula Benchmark Suite: Implications of Lightweight Neural Networks. IEEE Transactions on Computers, 2020, , 1-1. | 3.4 | 3 |

| # | ARTICLE | IF | CITATIONS |
|----|---|-----|-----------|
| 19 | Hardware accelerator systems for embedded systems. <i>Advances in Computers</i> , 2021, 122, 23-49. | 1.6 | 3 |
| 20 | Reliability-performance tradeoffs between 2.5D and 3D-stacked DRAM processors. , 2016, , . | | 2 |
| 21 | Measurement-Driven Methodology for Evaluating Processor Heterogeneity Options for Power-Performance Efficiency. , 2016, , . | | 1 |
| 22 | Thread-Aware Area-Efficient High-Level Synthesis Compiler for Embedded Devices. , 2021, , . | | 0 |